Product data sheet

BALVER ZINN®

OT2-SAC3-T3

Rev: 15.2

Date 2025.09.02
Language English
SDS 950611

BALVERZINN.COM

SUMMARY

Pb-free - Premium latest technology No-Clean solder paste - Halide/Halogen free

PASTE	OT2-SAC3-T3
PROCESS	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	8
Industrial electronics	9
Hi-Rel electronics (automotive)	9

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	9
Pb-free process N2	9
Vapor phase process	7
Shiny joint appearance	8
Cosmetic cleanliness	9
ICCT compatible	9
Conformal coating	8

Legend	
Especially made for this purpose	9 - 10
Generally qualified for this purpose	7 - 8
Generally usable, but not the best choice	5 - 6
Generally not usable for this purpose	3 - 4
Wrong choice	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

4-10 °C

CLASSIFICATION		
DIN-EN-29454-1: 1994		1.1.3.C
IPC-J-STD-004-A: 2004		ROL0
IPC-J-STD-005: 1995 (Powder)		T3
Particle size	[µm]	25-45

PROPERTIES			
Flux code			OT2
Alloy Code			SAC3
Alloy composition			Sn96.5Ag3Cu0.5
Liquidus		[°C]	219
Solidus		[°C]	217
Recommended peak temp.		[°C]	232-260
Acid number		[mg KOH/g]	139.5
Flux		[% w/w]	12
Residues			Colorless
Tackiness Malcom TK1	JIS-Z-3284	[gf] @ 0h	120

TEST REPORTS			
IPC/ANSI-J-STD-005			Compliant
Certificate of Compliance			Website
Declaration of Conformity 2011/65/EU (RoHS)			Available
Application Note			EN/DE
Copper Mirror	IPC-TM-650 2.3.32		Pass
Halides	IPC-TM-650 2.3.33	[Silver Chromate]	Pass
Halide	IPC-TM-650 2.3.35.1	[Fluoride by Spot]	Pass
Copper Corrosion	IPC-TM-650 2.6.15		Pass
SIR	IPC-TM-650 2.6.3.3		Pass
ECM	IPC-TM-650 2.6.14.1		Pass

PACKAGING AND STORAGE		
Packaging jar	PP [g]	500
Packaging cartridge	HDPE [g]	650
Packaging cartridge	HDPE [g]	1300
Packaging Cassette Pro-Flow	[g]	800
Minimum shelf-life in months	4-10 °C	-
Minimum shelf-life in months	4-10 °C	12